CLAIMS

1. A sealing sheet with separators on both surfaces, comprising:

a sealing sheet,

a separator A laminated on one surface of the sealing sheet, and

a separator B laminated on the other surface of the sealing sheet; and

satisfying the following formula (1) when the peel strength between the sealing sheet and the separator A is F1, the peel strength between the sealing sheet and the separator B is F2, the thickness of the sealing sheet is t, and the area of the sealing sheet is A:

(1) $0 < F2\ (N/20\ mm) \times A\ (m^2) \times t\ (mm) < 10.0\ (Nm^2)$

(wherein, F1 < F2 is satisfied.)

2. A method for manufacturing a semiconductor device, comprising:

a step A of preparing a laminate in which a semiconductor chip is fixed on a support,

a step B of preparing the sealing sheet with separators on both surfaces according to claim 1,

a step C of peeling the separator A from the sealing sheet with separators on both surfaces to obtain a sealing

sheet with a separator on one surface,

a step D of arranging the sealing sheet with a separator on one surface on the semiconductor chip of the laminate so that the surface where the separator A of the sealing sheet with a separator on one surface is peeled faces the surface of the semiconductor chip of the laminate,

a step E of embedding the semiconductor chip in the sealing sheet to form a sealed body in which the semiconductor chip is embedded in the sealing sheet, and

a step F of peeling the separator B.